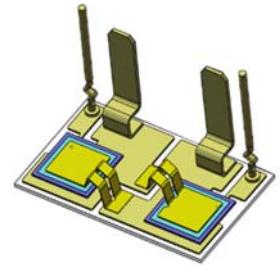


DBC070CxxKQ-KGxC

Description

- 1) Components adopt vacuum welding to well control void and rated voltage up to 1600V.
- 2) A package of two inverse parallel SCRs.
- 3) Thyristor chips are welding on the ceramic copper clad laminate, products with high electricity ability, excellent heat dissipation ability.



Typical Application

Constant temperature system, CNC machine, remote control system, lighting control, power compensation and so on.

Absolute Maximum Ratings (Packaged into modules, unless otherwise specified, $T_{CASE}=25^\circ\text{C}$)

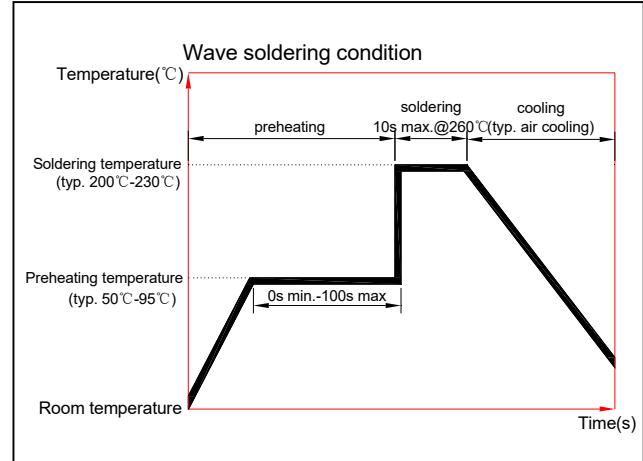
| Parameter | Test Conditions | Symbol | Values | | Unit |
|--|------------------------|--------------|----------|------|------------------------|
| | | | 12 | 16 | |
| Operating junction temperature range | | T_J | -40~+125 | | °C |
| Repetitive peak off-state voltage | $T_J=25^\circ\text{C}$ | V_{DRM} | 1200 | 1600 | V |
| Repetitive peak reverse voltage | $T_J=25^\circ\text{C}$ | V_{RRM} | 1200 | 1600 | V |
| Non-repetitive peak off-state voltage | $T_J=25^\circ\text{C}$ | V_{DSM} | 1300 | 1700 | V |
| Non-repetitive peak reverse voltage | $T_J=25^\circ\text{C}$ | V_{RSM} | 1300 | 1700 | V |
| Average on-state current | $T_C=80^\circ\text{C}$ | $I_{T(AV)}$ | 70 | | A |
| RMS on-state current | $T_C=80^\circ\text{C}$ | $I_{T(RMS)}$ | 110 | | A |
| Non-repetitive surge peak on-state current | $t_P=10\text{ms}$ | I_{TSM} | 1400 | | A |
| I^2t value for fusing | $t_P=10\text{ms}$ | I^2t | 9800 | | A^2s |
| Critical rate of rise of on-state current | $I_G=2 \times I_{GT}$ | di/dt | 150 | | $\text{A}/\mu\text{s}$ |

Electrical Characteristics (Packaged into modules, unless otherwise specified, $T_{CASE}=25^\circ\text{C}$)

| Parameter | Test Conditions | Symbol | Values | Unit |
|-----------------------------------|--|--------------------------|------------------------|---------------------|
| Peak on-state voltage | $I_{TM}=210\text{A}, t_P=380\mu\text{s}$ | V_{TM} | ≤ 1.8 | V |
| Repetitive peak off-state current | $V_D=V_{DRM}$ $T_C=25^\circ\text{C}$ $T_C=125^\circ\text{C}$ | I_{DRM1} I_{DRM2} | ≤ 50 ≤ 10 | μA mA |

Soldering Process Requirements

| a. Hand soldering iron welding | |
|--|--------|
| Soldering temperature | ≤260°C |
| Soldering time | ≤10s |
| b. Wave soldering (see figure at right) | |
| Preheating temperature | ≤125°C |
| Preheating time | ≤100s |
| Soldering temperature | ≤260°C |
| Soldering time | ≤10s |



Working Conditions

1) No severe mechanical shock as impact and drop off in the process of transportation, storage and working of product.

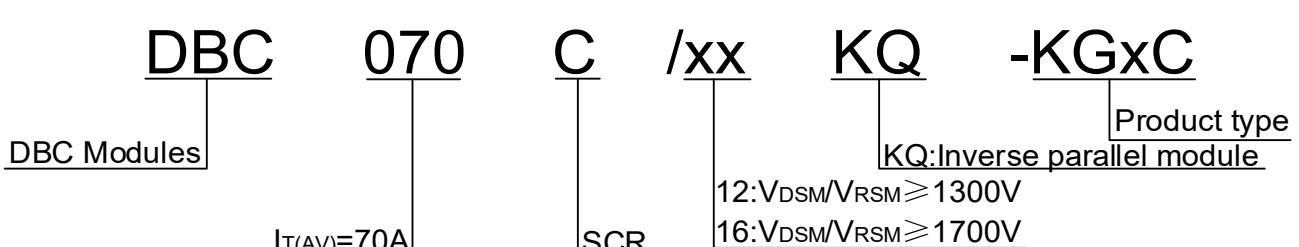
2) Storage conditions

Temperature: 5~40°C

Relative humidity: ≤45%

Storage time: 3 days for the open package; 3 months for the closed package

Ordering Information



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